

Title (en)

SENSOR COMPRISING A PREFERABLY MULTILAYERED CERAMIC SUBSTRATE AND METHOD FOR PRODUCING IT

Title (de)

SENSOR MIT EINEM VORZUGSWEISE MEHRSCHICHTIGEN KERAMIKSUBSTRAT UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)

CAPTEUR COMPORTANT UN SUBSTRAT CÉRAMIQUE DE PRÉFÉRENCE MULTICOUCHE ET PROCÉDÉ DE FABRICATION CORRESPONDANT

Publication

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Application

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Abstract (en)

[origin: WO2012072070A2] A sensor comprises a preferably multilayered ceramic substrate (2) and at least one sensor element (1) arranged in, at or on the ceramic substrate (2). Contact can be made with the sensor element (1) via a metallic contact (6), wherein the metallic contact (6) is produced by means of a soldering connection that electrically connects the contact (6) to the sensor element (1) and in the process produces a fixed mechanical connection of the contact (6) relative to the ceramic substrate (2). A method for producing the sensor according to the invention is furthermore claimed.

IPC 8 full level

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CPC (source: EP US)

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Citation (examination)

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- JP S60187046 A 19850924 - FUJITSU LTD
- JP H03147357 A 19910624 - TOSHIBA CORP
- US 5036431 A 19910730 - ADACHI KAZUMASA [JP], et al

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